

Title (en)

METHOD FOR CONTACTING AN ELECTRICALLY CONDUCTIVE PAPER STRUCTURE, COMPOSITE BODY AND USE

Title (de)

VERFAHREN ZUR KONTAKTIERUNG EINES ELEKTRISCH LEITENDEN PAPIERGEFÜGES, VERBUNDKÖRPER UND VERWENDUNG

Title (fr)

PROCÉDÉ DE MISE EN CONTACT D'UNE STRUCTURE DE PAPIER ÉLECTRIQUEMENT CONDUCTRICE, CORPS COMPOSITE ET UTILISATION

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Abstract (en)

[origin: WO2023016945A1] The invention relates to a composite body, comprising: a support plate (1) having recesses, an upper main surface and a lower main surface; and an electrically conductive paper structure (4) adjoining the upper main surface of the support plate, wherein: the electrically conductive paper structure (4) has at least one conductor track (3) facing the upper main surface of the support plate; and conductor elements (2) are introduced into the recesses of the support plate such that the conductor elements (2) terminate flush with the upper main surface of the support plate (1), the conductor elements (2) are in electrical contact with the at least one conductor track (3) of the electrically conductive paper structure (4), and the conductor elements (2) are contactable with a current source from the lower main surface of the support plate (1).

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